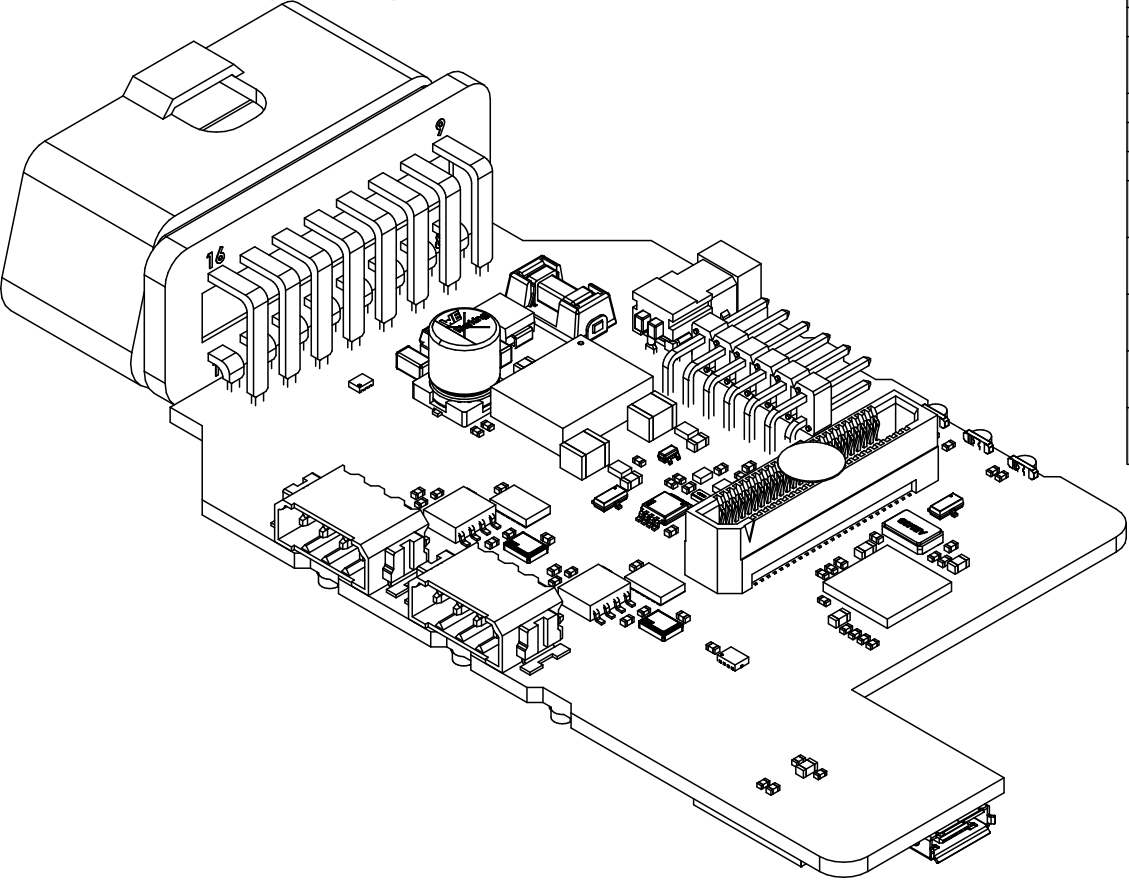


# PROJECT OVERVIEW

Name: KUKSA CANOPi  
Identifier: BaseBoard  
Version: V1.1  
Revision: A  
Variant: [All Variants]  
Initial Date: 1.12.2021  
Plot Date: 18.01.2022 - 12:08

View from Front side (Scale 3:2)

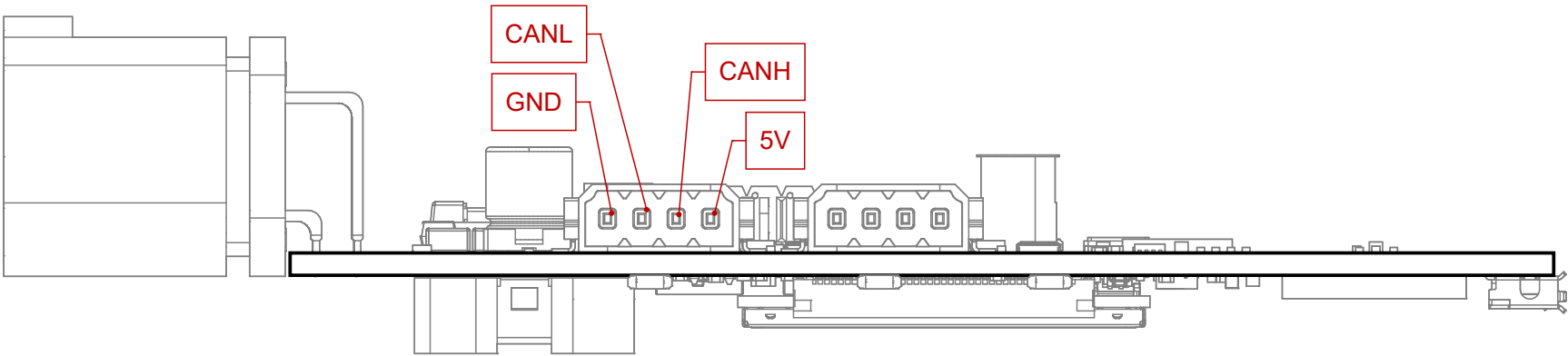


Bill Of Materials			
Line #	Designator	Comment	Quantity
1	BT700	KEYSTONE - 1060	1
2	C300, C303, C304, C305, C306, C307, C308, C309, C402, C407, C500, C501, C502, C503, C506, C507, C509, C606, C607, C610, C611, C612, C613, C614, C615, C616, C700	CAP 0402 100n -10% +10% 6.3V X7R	27
3	C301, C302, C310, C311, C405	CAP 0402 27p -2% +2% 25V C0G	5
4	C400, C403, C510, C605, C609	CAP 0603 10µF -20% +20% 6.3V X5R	5
5	C401, C404, C406, C504, C505, C508, C617	CAP 0603 1u -10% +10% 10V X7R	7
6	C511, C512	CAP 0402 15p -2% +2% 25V C0G	2
7	C600	CAP2625 47u -20% +20% 50V	1
8	C601	CAP 0603 100n -10% +10% 50V X7R	1
9	C602, C603	CAP 1206 10u -10% +10% 50V X5R	2
10	C604, C608	CAP 1210 100µF +/-20% 16V X5R	2
11	D300, D301, D500	VISHAY - VBUS052CD-FAH-GS08	3
12	D400, D602, D603	WUERTH ELEKTRONIK - 155124RS73200	3
13	D501, D605	INFINEON - BAT64-04	2
14	D502, D503, D504	WUERTH ELEKTRONIK - 155124VS73200	3
15	D600	VS-15MQ040NTRPBF	1
16	D601	STMICROELECTRONICS - SMBJ24A-TR	1
17	D604	RBE1VAM20ATR	1
18	D700	INFINEON - BAT64-05	1
19	F600	LITTELFUSE - 15403.5DRT.	1
20	FB500	MURATA - BLM18AG121SN1D	1
21	J400	629105150921	1
22	J600	694101308002	1
23	J601	AMPHENOL - 10129382	1
24	J700	SAMTEC - ERF8-025-07.0-L-DV-TR	1
25	JP500	Solder Jumper 0402 unbestückt	1
26	JP600	Solder Jumper Triple 0402 with Assembly between 1 and 2	1
27	P400	TE CONNECTIVITY - 2199119-3	1
28	Q400, Q401, Q600, Q601, Q602	DIODES INCORPORATED - 2N7002T	5

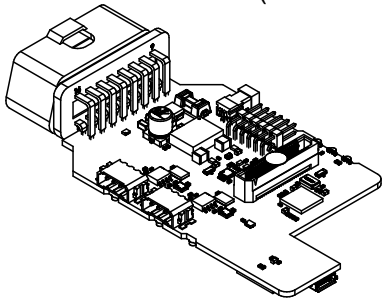
Bill Of Materials			
Line #	Designator	Comment	Quantity
29	R300, R301, R303, R304, R404, R500, R501	RES 0402 60R4 1% 0W0625	7
30	R302, R305, R514, R613	RES 0402 100R 1% 63mW	4
31	R306, R307, R504, R505, R506, R509	RES 0402 10K 1% 0W0625	6
32	R400, R401, R405, R700, R701	RES 0402 4K7 1% 0W0625	5
33	R402, R508, R511, R513, R515	RES 0402 1K 1% 0W0625	5
34	R403, R600, R601, R602	RES 0402 33K 1% 0W0625	4
35	R502, R606, R607, R611, R612	RES 0402 330K 1% 0W0625	5
36	R503	RES 0402 62K 1% 0W0625	1
37	R507, R510, R512, R516, R517, R518, R519, R520, R604, R608, R609, R610, R614	RES 0402 100K 1% 0W0625	13
38	R603	RES 0402 47K5 1% 0W0625	1
39	R605	RES 0402 78K7 1% 0W0625	1
40	S600, S601	C & K - PCM12SMTR	2
41	SW500, SW600	EVQ-P7J01P	2
42	U300, U302	MICROCHIP - MCP2542FD/4FD	2
43	U301, U303	MICROCHIP - MCP2518FD	2
44	U400	ON SEMICONDUCTOR - FSUSB43L10X	1
45	U500	MCP2562-E/MF	1
46	U501	OBD SOLUTIONS - STN2120	1
47	U600	ANALOG DEVICES - LTM8024EY#PBF	1
48	U601, U602	VISHAY - SIP32408	2
49	U603, U605, U606	SN74LVC1G07DRYR	3
50	U604	SN74LVC1G27DBVR	1
51	U700	PCF85063ATT/AJ	1
52	X300, X301	PHOENIX CONTACT - PTSM 0,5/ 4-HH-2,5-SMD R32	2
53	X400	JST - SCZW-7SA-1K(HF)	1
54	X500	ABM3B-16.000MHZ-B2-T	1
55	X501	COMTECH ELECTRONIC - OBD-2 Stifblock	1
56	Y300, Y301	ECS-200-18-33Q-DS	2
57	Y700	ABRACON - ABS05-32.768KHZ-9-T	1

# PCBA VIEW 1

View from Front side (Scale 2:1)



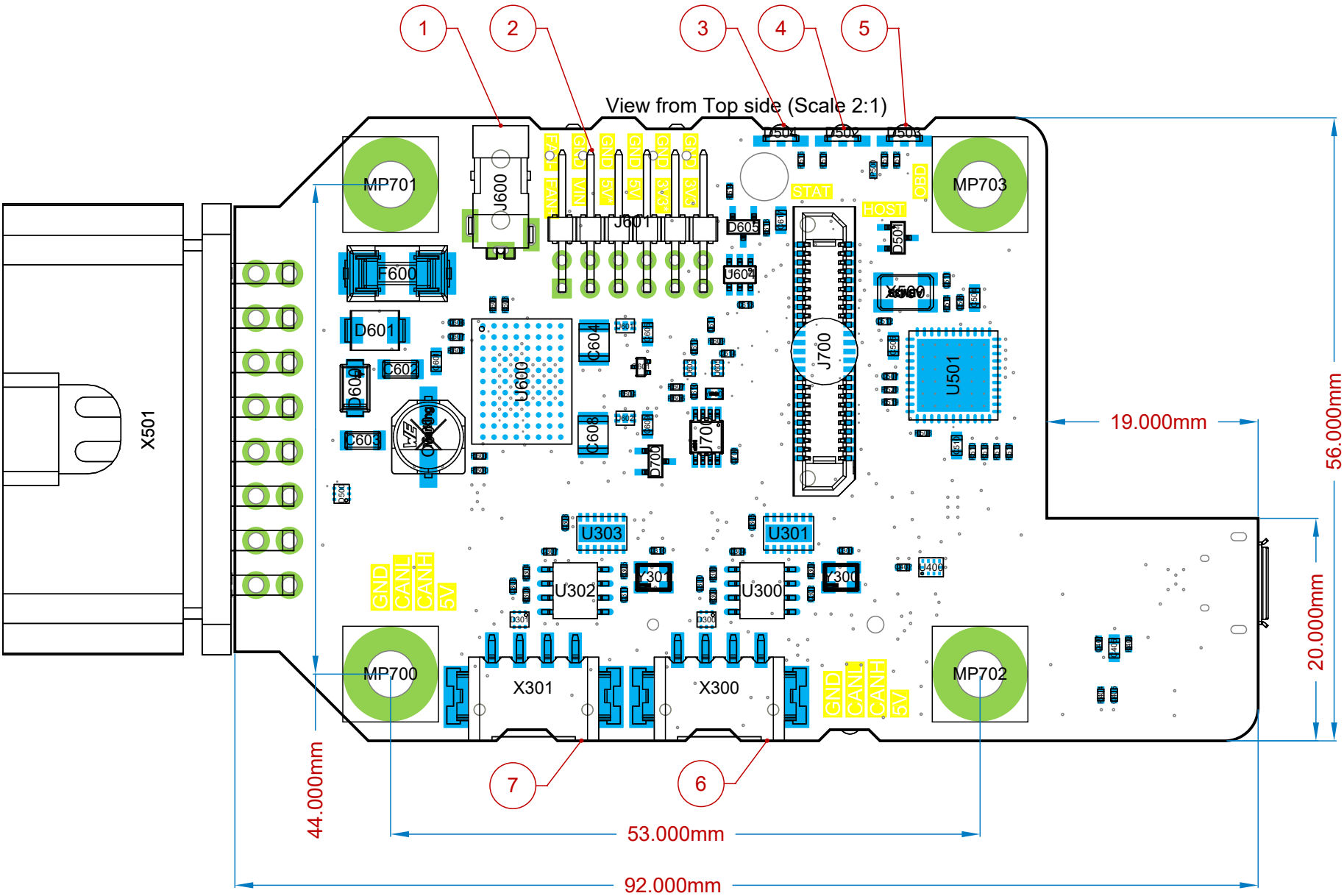
View from Front side (Scale 0.5)



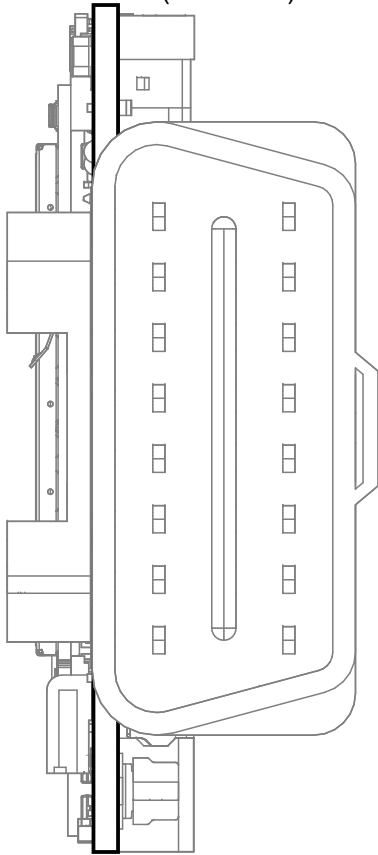
Notes:

- ① DC Power jack (3.5mm OT)
- ② Power connectors
- ③ OBD Status LED
- ④ OBD Host active LED
- ⑤ OBD Activity LED
- ⑥ CAN FD Connector
- ⑦ CAN FD Connector

View from Top side (Scale 2:1)



View from Left side (Scale 2:1)



Project: KUKSA CANOPi

Identifier: BaseBoard Version: V1.1 Revision: A Variant: [All Variants]

Document Size: A3  
Unit: Millimeters

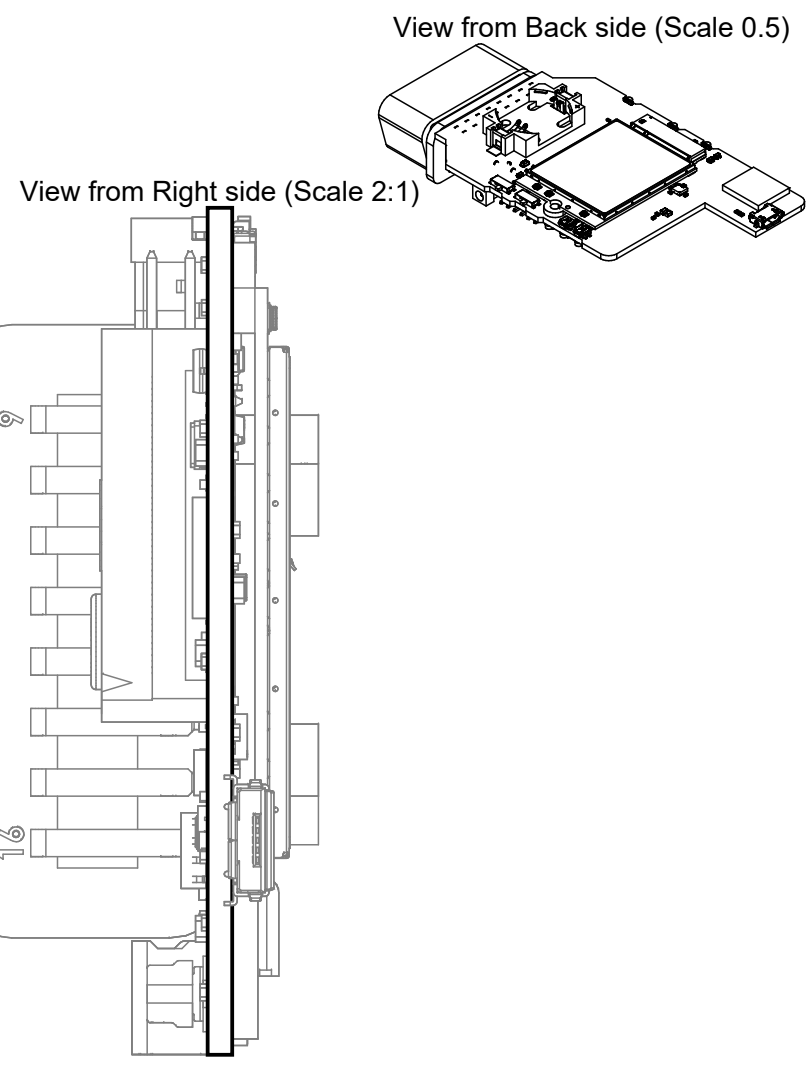
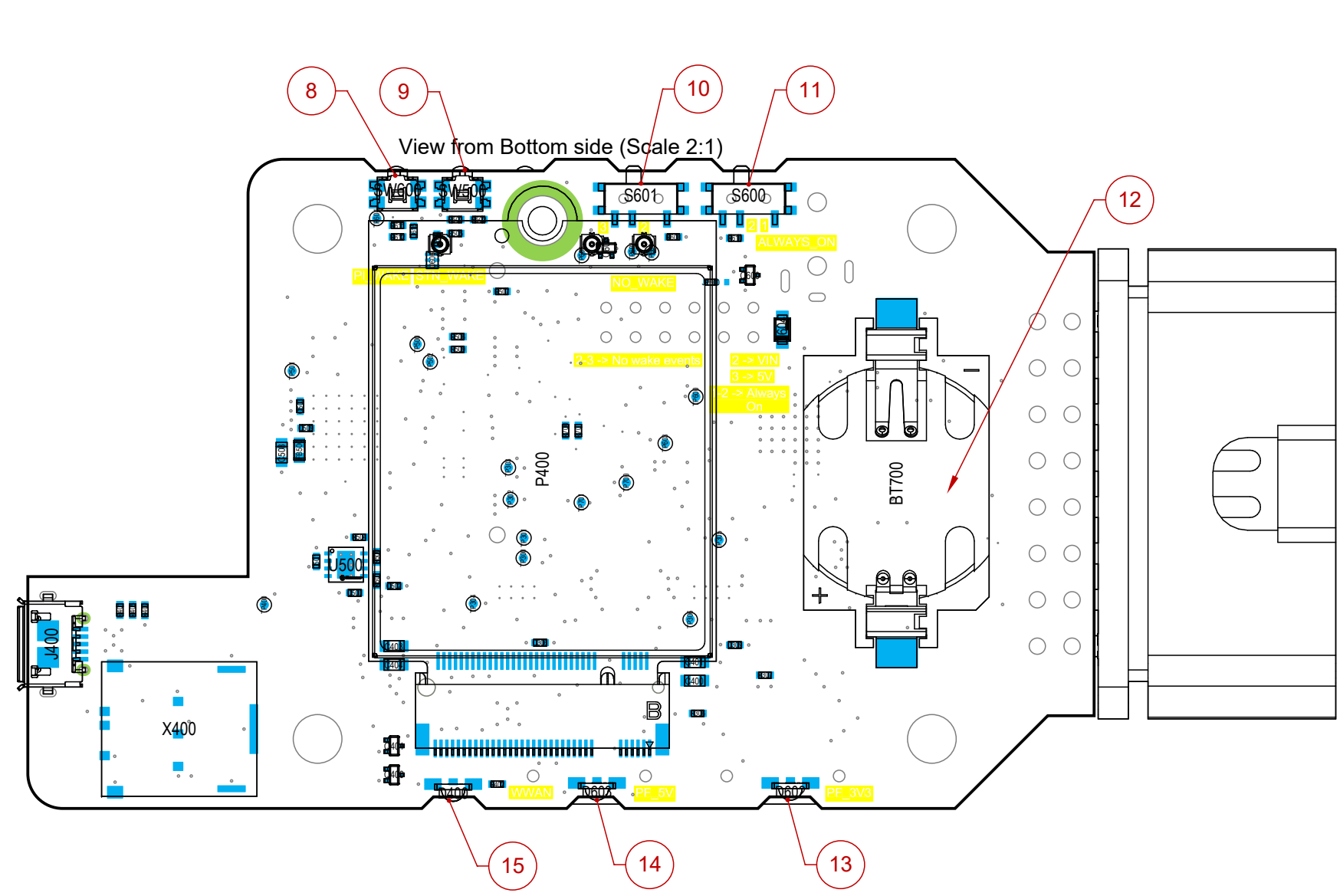
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Initial Date: 1.12.2021

Document Name: BaseBoard.PCBDwf  
PCB File Name: BaseBoard.PcbDoc

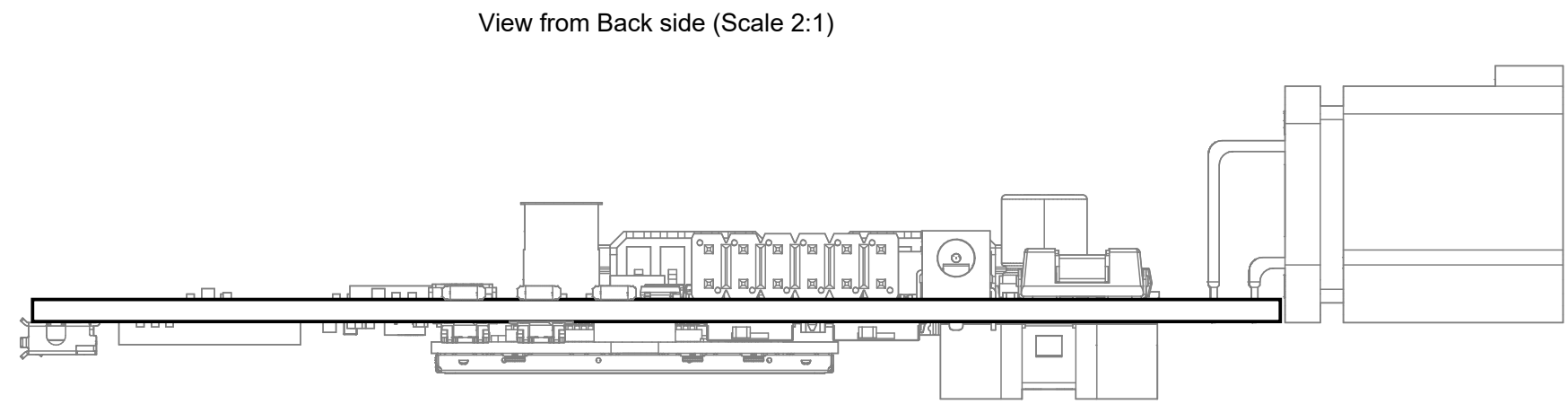
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PCB SVN: Not in version control



# PCBA VIEW 2

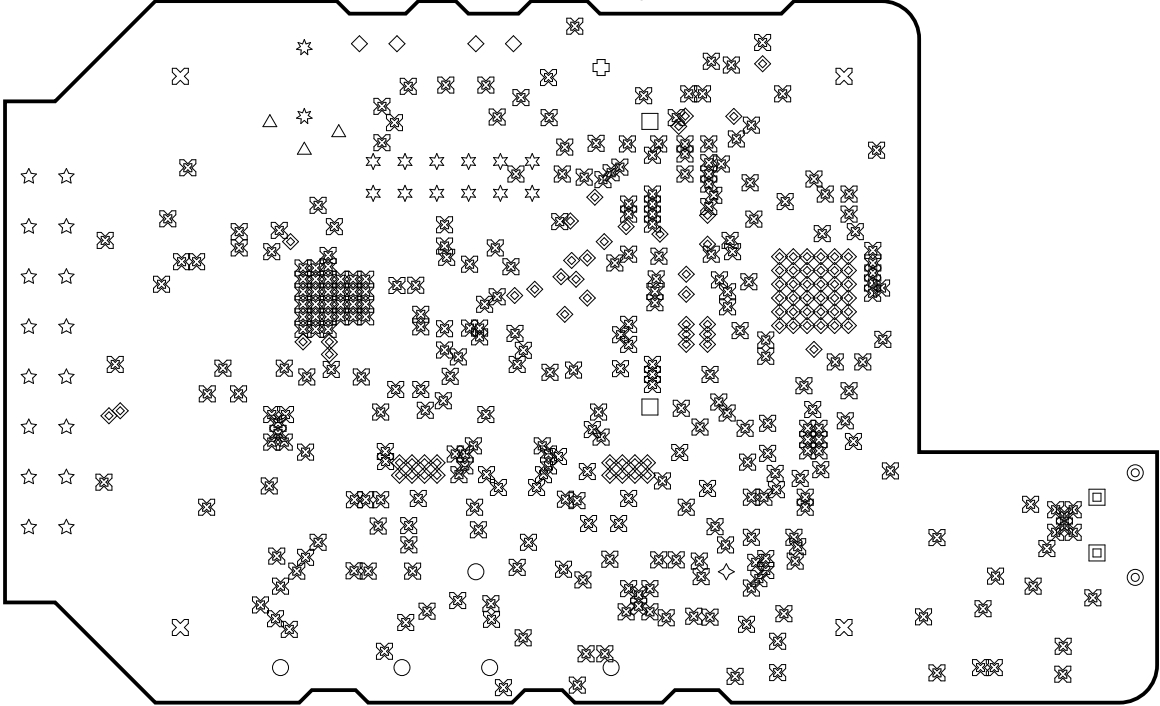


- Notes:
- 8 "PI Wake" - Push button
  - 9 "STN Wake" - Push button
  - 10 No Wake events
  - 11 Always On (No power down)
  - 12 Coin cell holder (CR2032)
  - 13 Power Fail 3V3 LED
  - 14 Power Fail 5V LED
  - 15 WWAN



# DRILL INFORMATION

Drill Drawing (Top View | Scale 1.65652175929679)



Board Outline

Technology	Selection
milling	x
v-scoring	
mixed (defined in Gerber file)	
mixed (defined in Draftsman drawing)	
Separation PCB Manufacturer	Selection
each PCB	
Assembly Panel	x
Separation Assembly House	Selection
each PCBA	x
Assembly Panel	

Via - Plugging / Filling / Tenting

IPC 4761 Type	Description	Selection
not used	All Vias without Plugging/Filling/Tenting	x
I(a)	Tented - Single Sided	
I(b)	Tented - Double Sided	
II(a)	Tented & Covered - Single Sided	
II(b)	Tented & Covered - Double Sided	
III(a)	Plugged - Single Sided	
III(b)	Plugged - Double Sided	
IV(a)	Plugged & Covered - Single Sided	
IV(b)	Plugged & Covered - Double Sided	
V	Filled (Fully Plugged)	
VI(a)	Filled & Covered (Fully Plugged) - Single Sided	
VI(b)	Filled & Covered (Fully Plugged) - Double Sided	
VII	Filled & Capped	
multiple used	Definded in Gerber file	

Drill Table

Symbol	Via / Pad	Count	Hole Size	Hole Type	Drill Layer Pair	Plated	Hole Tolerance
⊗	Via	323	0.300mm	Round	Top Layer - Bottom Layer	Plated	None
◇	Via	86	0.200mm	Round	Top Layer - Bottom Layer	Plated	None
⊕	Pad	1	4.400mm	Round	Top Layer - Bottom Layer	Plated	None
⊗	Pad	4	4.300mm	Round	Top Layer - Bottom Layer	Plated	None
☆	Pad	2	1.700mm	Round	Top Layer - Bottom Layer	Non-Plated	None
◇	Pad	1	1.600mm	Round	Top Layer - Bottom Layer	Plated	None
☆	Pad	16	1.500mm	Round	Top Layer - Bottom Layer	Plated	None
□	Pad	2	1.450mm	Round	Top Layer - Bottom Layer	Plated	None
○	Pad	5	1.100mm	Round	Top Layer - Bottom Layer	Plated	None
☆	Pad	12	1.020mm	Round	Top Layer - Bottom Layer	Plated	None
◇	Pad	4	0.900mm	Round	Top Layer - Bottom Layer	Non-Plated	None
⊙	Pad	2	0.825mm	Slot	Top Layer - Bottom Layer	Plated	None
△	Pad	3	0.800mm	Slot	Top Layer - Bottom Layer	Plated	None
▣	Pad	2	0.650mm	Slot	Top Layer - Bottom Layer	Plated	None
		463 Total					

16. Hole size is final dimension.

# LAYERSTACK INFORMATION

Layer Stack Legend 1

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.0254mm	SM-001	Solder Mask	GTS
CF-004	Top Layer	0.0350mm		Signal	GTL
Prepreg		0.0711mm	PP-006	Dielectric	
Prepreg		0.0711mm	PP-006	Dielectric	
CF-004	Int2 (Sign)	0.0350mm		Signal	G1
Core		1.2000mm	Core-009	Dielectric	
CF-004	Int3 (Sign)	0.0350mm		Signal	G2
Prepreg		0.0711mm	PP-006	Dielectric	
Prepreg		0.0711mm	PP-006	Dielectric	
CF-004	Bottom Layer	0.0350mm		Signal	GBL
Surface Material	Bottom Solder	0.0254mm	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.6753mm					

Surface Finish

Material	Selection
ENIG (chem. Ni/Au)	x
Chemical Tin	
ENEPIG	
HASL - Lead free	
HASL + Pb	
Other:	

Silkscreen

Side	Color / Material	Selection
Top	white	x
Bottom	white	x

Soldermask

Side	Color / Material	Selection
Top	green	x
Bottom	green	x

17. Layer stack thickness is final dimension

# ADDITIONAL INFORMATION

ID	Process / Requirement	Selection / Definition
1	Halogen free (low Hal)	-
2	Warp & Weft direction	-
3	Temper PCB for better planarity	-
4	X-Ray	-
5	Serial Number	-
6	Electrical Tests	100% of PCBs
7	RoHS	yes
8	UL94	-
9	Datecode (PCB manufacturing)	yes (calender week / year)
10	Manufacturer Marking	-
11	Sideplating / Metallized Edges	-
12	Controlled Impedance	-
13	Soldering process	-
14	...	
15		
16		
17		
18		



1

2